

## PROTECTION PRODUCTS

### Description

The SMF series TVS arrays are designed to protect sensitive electronics from damage or latch-up due to ESD and other voltage-induced transient events. They are designed for use in applications where board space is at a premium. Each device will protect up to five lines. They are unidirectional devices and may be used on lines where the signal polarities are above ground.

TVS diodes are solid-state devices designed specifically for transient suppression. They feature large cross-sectional area junctions for conducting high transient currents. They offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

The SMF series devices may be used to meet the immunity requirements of IEC 61000-4-2, level 4. The small SC70 package makes them ideal for use in portable electronics such as cell phones, PDA's, notebook computers, and digital cameras.

### Features

- ◆ ESD protection for data lines to **IEC 61000-4-2 (ESD) 15kV (air), 8kV (contact)**
- ◆ Small package for use in portable electronics
- ◆ Protects five I/O lines
- ◆ Working voltage: 5V
- ◆ Low leakage current
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon-avalanche technology

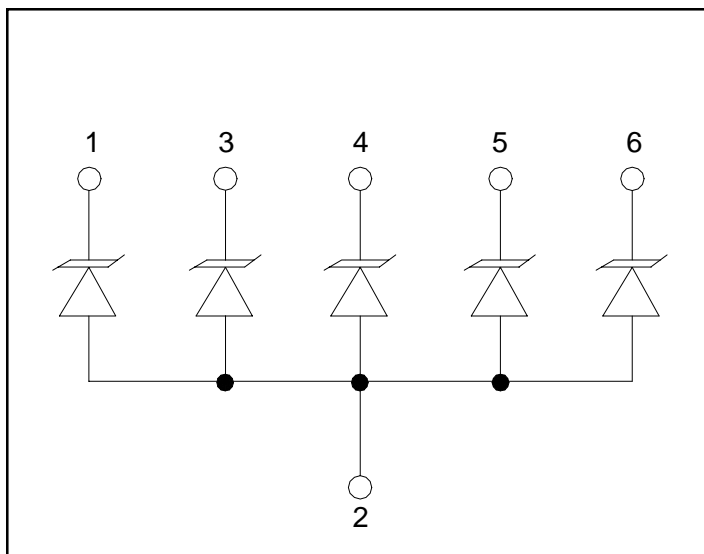
### Mechanical Characteristics

- ◆ EIAJ SC70-6L package
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Marking : Marking Code
- ◆ Packaging : Tape and Reel per EIA 481

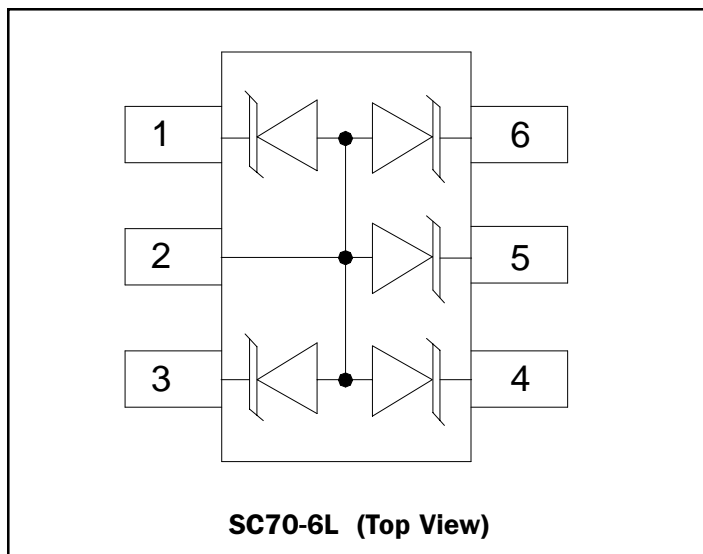
### Applications

- ◆ Cellular Handsets & Accessories
- ◆ Cordless Phones
- ◆ Personal Digital Assistants (PDA's)
- ◆ Notebooks & Handhelds
- ◆ Portable Instrumentation
- ◆ Digital Cameras
- ◆ Peripherals
- ◆ MP3 Players

### Circuit Diagram



### Schematic & PIN Configuration



**PROTECTION PRODUCTS**
**Absolute Maximum Rating**

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu s$ )	$P_{pk}$	100	Watts
Peak Pulse Current ( $t_p = 8/20\mu s$ )	$I_{pp}$	8	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$V_{ESD}$	20 15	kV
Lead Soldering Temperature	$T_L$	260 (10 seconds)	°C
Operating Temperature	$T_J$	-55 to +125	°C
Storage Temperature	$T_{STG}$	-55 to +150	°C

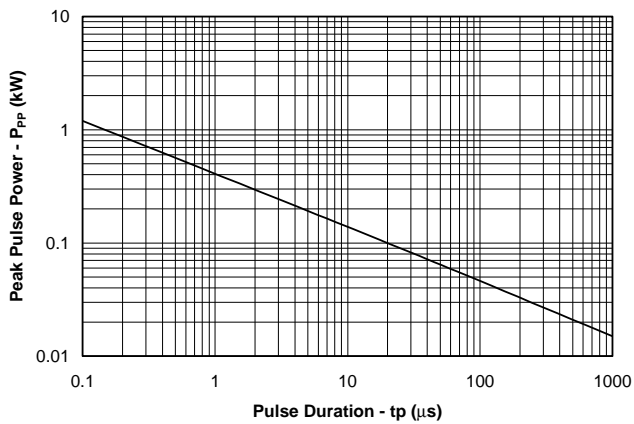
**Electrical Characteristics**

<b>SMF05C</b>						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$				5	V
Reverse Breakdown Voltage	$V_{BR}$	$I_t = 1mA$	6			V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5V, T=25^\circ C$			5	$\mu A$
Clamping Voltage	$V_C$	$I_{pp} = 5A, t_p = 8/20\mu s$			9.8	V
Clamping Voltage	$V_C$	$I_{pp} = 8A, t_p = 8/20\mu s$			12.5	V
Junction Capacitance	$C_J$	$V_R = 0V, f = 1MHz$			130	pF

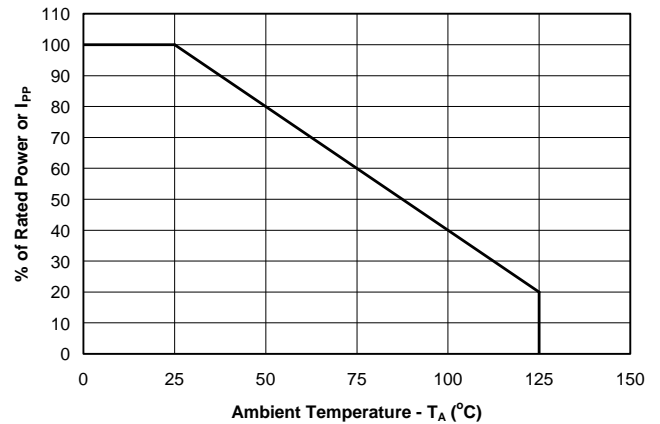
## PROTECTION PRODUCTS

### Typical Characteristics

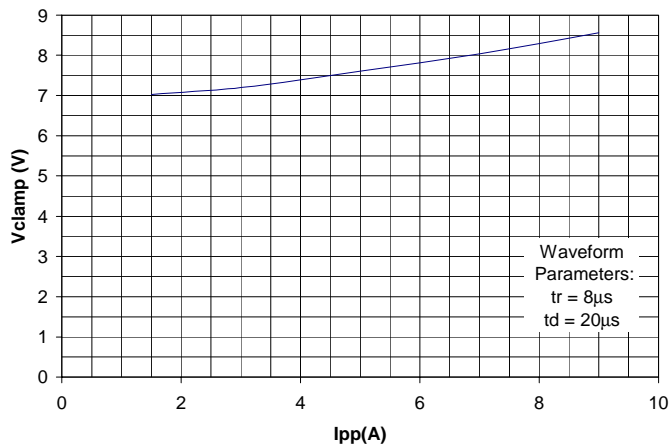
**Non-Repetitive Peak Pulse Power vs. Pulse Time**



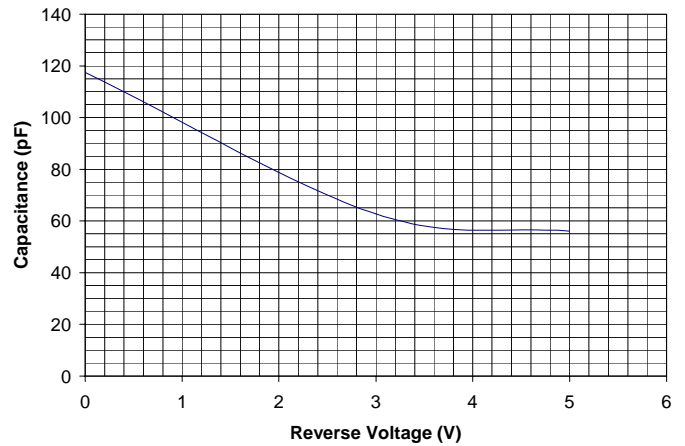
**Power Derating Curve**



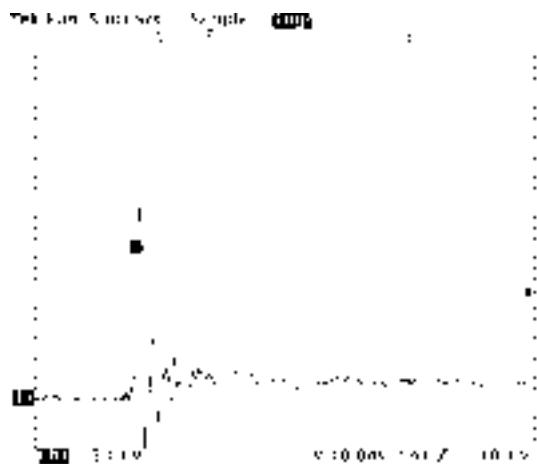
**Clamping Voltage vs. Peak Pulse Current**



**Junction Capacitance vs. Reverse Voltage**



**ESD Clamping Characteristics  
(8kV Contact Discharge per IEC 61000-4-2)**



## PROTECTION PRODUCTS

### Applications Information

#### Device Connection for Protection of Five Data Lines

The SMF05C is designed to protect up to five unidirectional data lines. The device is connected as follows:

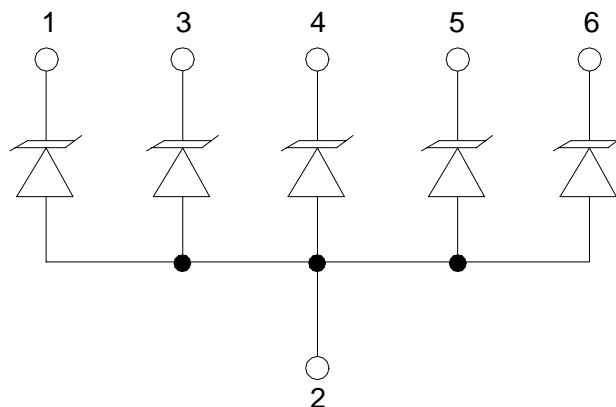
1. Unidirectional protection of five I/O lines is achieved by connecting pins 1, 3, 4, 5 and 6 to the data lines. Pin 2 is connected to ground. The ground connection should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.

#### Circuit Board Layout Recommendations for Suppression of ESD.

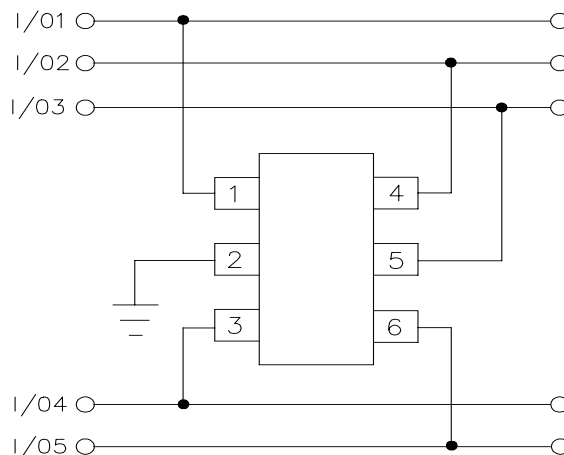
Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

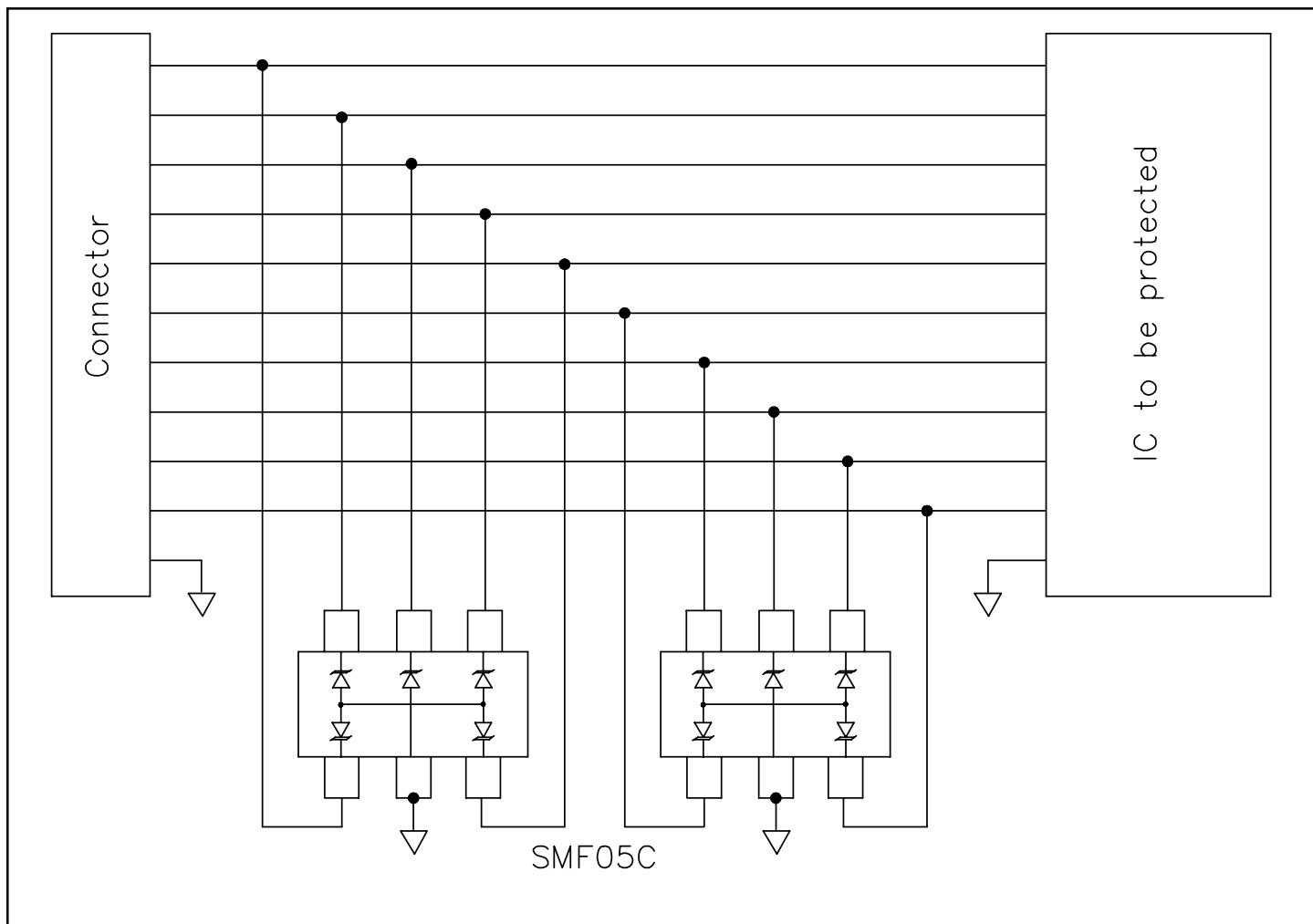
- Place the SMF05C near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the SMSxxC and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

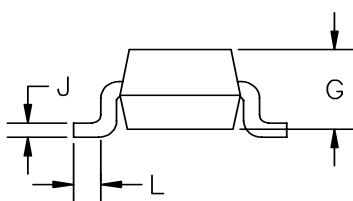
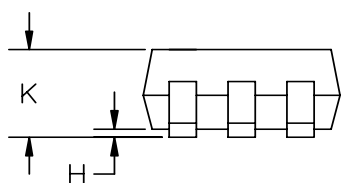
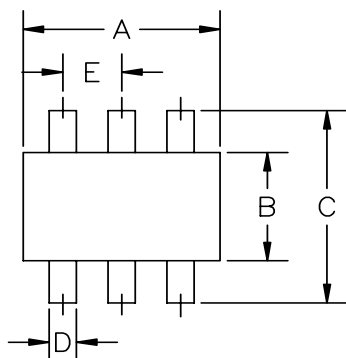
#### SMF05C Circuit Diagram



#### Protection of Five Unidirectional Lines



**PROTECTION PRODUCTS**
**Typical Applications**


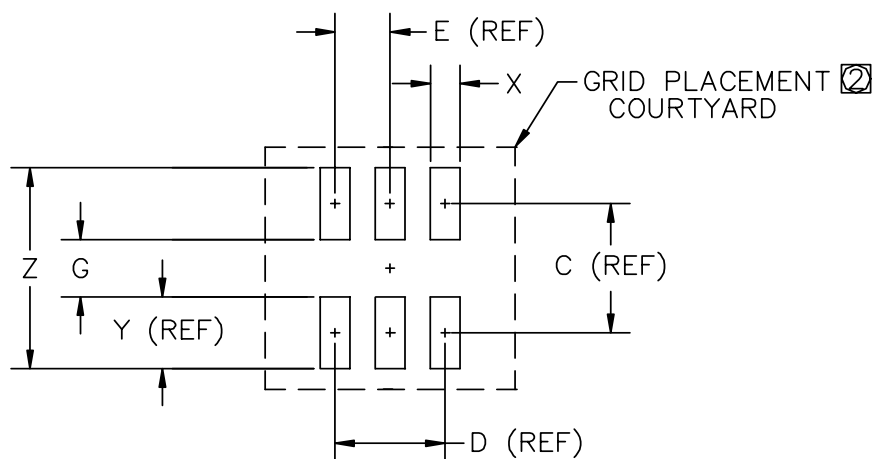
**PROTECTION PRODUCTS**
**Outline Drawing - SC70-6L**


DIMENSIONS ①					NOTE
DIM <sup>N</sup>	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.071	.087	1.80	2.20	—
B	.045	.053	1.15	1.35	—
C	.071	.094	1.80	2.40	—
D	.006	.012	.150	.300	—
E	.026	BSC	.650	BSC	—
G	.031	.039	.800	1.00	—
H	0.00	.004	0.00	.100	—
J	.004	.007	.100	.180	—
K	.031	.043	.800	1.10	—
L	.004	.012	.100	.300	—

JEDEC EIAJSC70

② PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH AND METAL BURR.

① CONTROLLING DIMENSIONS: MILLIMETERS.

**Land Pattern - SC70-6L**


DIMENSIONS ①					
DIM <sup>N</sup>	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
C	—	.063	—	1.60	—
D	—	.052	—	1.30	—
E	—	.026	—	.65	—
G	—	.028	—	.70	—
X	—	.014	—	.35	—
Y	—	.035	—	.90	—
Z	—	.098	—	2.50	—

② GRID PLACEMENT COURTYARD IS 6 x 6 ELEMENTS (3 mm X 3 mm) IN ACCORDANCE WITH THE INTERNATIONAL GRID DETAILED IN IEC PUBLICATION 97.

① CONTROLLING DIMENSION: MILLIMETERS

**PROTECTION PRODUCTS****Marking Codes**

<b>Part Number</b>	<b>Marking Code</b>
SMF05C	F5C

Note:

(1) Pin 1 Identified with a dot

**Ordering Information**

<b>Part Number</b>	<b>Working Voltage</b>	<b>Qty per Reel</b>	<b>Reel Size</b>
SMF05C.TC	5V	3,000	7 Inch
SMF05C.TG	5V	10,000	13 Inch

**Contact Information**

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